CD54HC646...F PACKAGE

SCHS278B - APRIL 2003 - REVISED APRIL 2003

- 2-V to 6-V V_{CC} Operation (CD54HC646)
- 4.5-V to 5.5-V V_{CC} Operation (CD74HCT646)
- Wide Operating Temperature Range of -55°C to 125°C
- **Balanced Propagation Delays and Transition Times**
- Standard Outputs Drive Up To 15 LS-TTL
- Significant Power Reduction Compared to **LS-TTL Logic ICs**
- Inputs Are TTL-Voltage Compatible (CD74HCT646)
- Independent Registers for A and B Buses
- **Multiplexed Real-Time and Stored Data**
- **True Data Paths**

CD74HCT646 . . . M PACKAGE (TOP VIEW) 24 🛮 V_{CC} CLKAB [SAB II 2 23 CLKBA DIR Π 3 22**∏** SBA 21 TOE A1 **∏** 4 A2 **∏** 5 20**∏** B1 19**∏** B2 A3 ∏ 6 А4 Г 18**∏** B3 A5 **∏** 8 17**∏** B4 A6 🛮 9 16 B5 A7 **∏** 10 15**∏** B6 A8 **∏** 11 14**∏** B7 12 13**∏** B8 GND ∏

description/ordering information

The CD54HC646 and CD74HCT646 consist of bus-transceiver circuits with 3-state outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

Output-enable (OE) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{OE} is active (low). In the isolation mode (\overline{OE} high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function still is enabled and can be used to store data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to ${\sf V}_{\sf CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PAC	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC - M	Tape and reel	CD74HCT646M96	HCT646M
-55 C to 125 C	CDIP – F	Tube	CD54HC646F3A	CD54HC646F3A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



testing of all parameters.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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FUNCTION TABLE

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified†
X	X	Х	\uparrow	X	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	↑	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

[†] The data-output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



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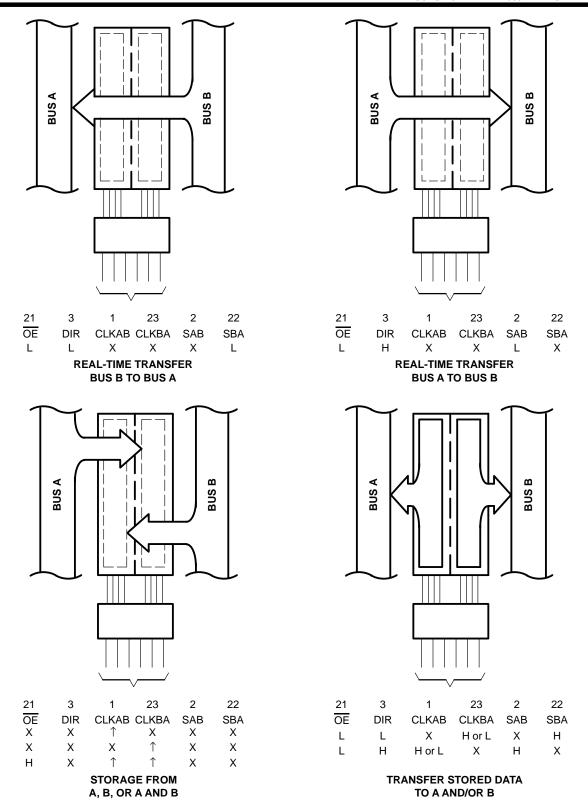
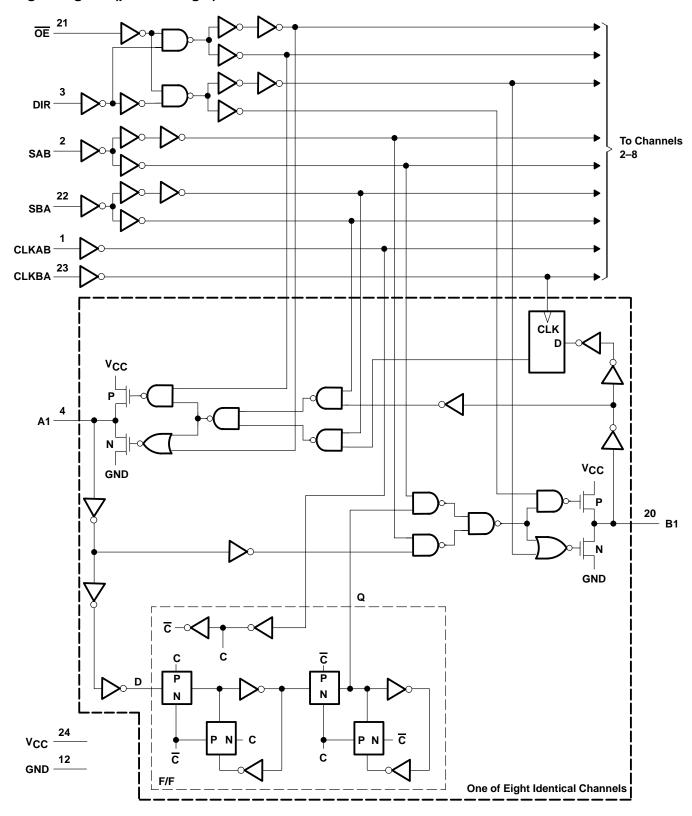


Figure 1. Bus-Management Functions



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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output drain current per output, I _O (V _O = 0 to V _{CC})	±35 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2) M package	46°C/W
Storage temperature range, T _{stq}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions for CD54HC646 (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	6	V
	Vcc	= 2 V	1.5		
٧ _{IH}	High-level input voltage	= 4.5 V	3.15		V
	Vcc	= 6 V	4.2		
	Vcc	= 2 V		0.5	
VIL	Low-level input voltage	= 4.5 V		1.35	V
	Vcc	= 6 V		1.8	
٧ _I	Input voltage		0	VCC	V
٧o	Output voltage		0	VCC	V
	Vcc	= 2 V		1000	
t _t	Input transition (rise and fall) time	= 4.5 V		500	ns
	VCC = 6 V				
TA	Operating free-air temperature		-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

recommended operating conditions for CD74HCT646 (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	٧
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
VI	Input voltage		VCC	V
٧o	Output voltage		VCC	V
t _t	Input transition (rise and fall) time		500	ns
TA	Operating free-air temperature	-55	125	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		vcc	T _A = 1	25°C	T _A = -55°C TO 125°C		T _A = −40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX		
			2 V	1.9		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48		5.2		5.34		
		I _{OL} = 20 μA	2 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
V _{OL}	$V_I = V_{IH}$ or V_{IL}		6 V		0.1		0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1		±1		±1	μΑ
loz	VO = VCC or 0		6 V		±0.5		±10		±5	μΑ
ICC	$V_I = V_{CC}$ or 0,	I _O = 0	6 V		8		160		80	μΑ
C _i		•			10		10		10	pF
Co					20		20		20	pF

electrical characteristics for CD74HCT646 over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcс	T _A = 25°C			T _A = -		T _A = -40°C TO 85°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
Voн	\/ı = \/u \ or \/u	$V_I = V_{IH} \text{ or } V_{IL}$		4.4			4.4		4.4		V
VОН	VI = VIH OI VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98			3.7		3.84		V
Val	VI = VIH or VIL	$I_{OL} = 20 \mu A$	4.5 V			0.1		0.1		0.1	V
VOL	AI = AIH OL AIL	$I_{OL} = 6 \text{ mA}$	4.5 V			0.26		0.4		0.33	V
ΙĮ	$V_I = V_{CC}$ to GND		5.5 V			±0.1		±1		±1	μΑ
loz	VO = VCC or 0		5.5 V			±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8		160		80	μΑ
∆l _{CC} †	One input at V _{CC} – 2.1 V, Other inputs at 0 or V _{CC}		4.5 V to 5.5 V		100	360		490		450	μΑ
C _i						10		10		10	pF
Co						20		20		20	pF

[†] Additional quiescent supply current per input pin, TTL inputs high, 1 unit load



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HCT INPUT LOADING TABLE

INPUT	UNIT LOAD
ŌĒ	1.3
DIR	0.75
CLKAB or CLKBA	0.6
SAB or SBA	0.45
A or B	0.3

[†] Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 360 μ A max at 25°C).

timing requirements for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

		vcc	T _A = 25°C		T _A = -55°C TO 125°C		T _A = -40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
		2 V		6		4		5	
fclock	Clock frequency	4.5 V		30		20		25	MHz
		6 V		35		23		29	
	Pulse duration, CLKBA or CLKAB high or low	2 V	80		120		100		ns
t _w		4.5 V	16		24		20		
		6 V	14		20		17		
		2 V	60		90		75		
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	12		18		15		ns
		6 V	10		15		13		
		2 V	35	·	55		45		
th	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	7	·	11		9		ns
		6 V	6		9		8		

timing requirements for CD74HCT646 over recommended operating free-air temperature range, V_{CC} = 4.5 V (unless otherwise noted) (see Figure 3)

		T _A =	T _A = 25°C		-55°C 25°C	5°C T _A = -40° 5°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		25		17		20	MHz
t _W	Pulse duration, CLKBA or CLKAB high or low	25		38		31		ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	12	·	18		15		ns
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	5	·	5		5		ns



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switching characteristics for CD54HC646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	T,	_A = 25°C	;	T _A = -	-55°C 25°C	T _A = -		UNIT
	(INI O1)	(0011 01)	CALACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
				2 V	6			4		5		
f			C _L = 50 pF	4.5 V	30			20		25		MHz
fmax				6 V	35			23		29		IVII IZ
			C _L = 15 pF	5 V		60						
				2 V			220		330		275	
	CLKBA or	A or B	C _L = 50 pF	4.5 V			44		66		55	
	CLKAB	7015		6 V			37		56		47	
			C _L = 15 pF	5 V		18						
				2 V			135		205		170	
.	A or B	B or A	C _L = 50 pF	4.5 V			27		41		34	no
^t pd	AOIB	BUIA		6 V			23		35		29	ns
			C _L = 15 pF	5 V		12						
				2 V			170		255		215	
	SBA or	A or B	C _L = 50 pF	4.5 V			34		51		43	
	SAB†	AUID		6 V			29		43		37	
			C _L = 15 pF	5 V		14						
				2 V			175		265		220	
	ŌĒ	A or B	C _L = 50 pF	4.5 V			35		53		44	
^t en	OE .	AUID		6 V			30		45		37	ns
			C _L = 15 pF	5 V		14						
				2 V			175		265		220	
4	ŌĒ	A == D	C _L = 50 pF	4.5 V			35		53		44	
^t dis	OE	A or B		6 V			30		45		37	ns
			C _L = 15 pF	5 V		14						
				2 V			60		90		75	
t _t		Any	C _L = 50 pF	4.5 V			12		18		15	ns
				6 V			10		15		13	

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



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switching characteristics for CD74HCT646 over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	Vcc	T,	դ = 25°C	;	T _A = -		T _A = -		UNIT
	(INFOT)	(001F01)	CAFACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
4			C _L = 50 pF	4.5 V	25			17		20		MHz
f _{max}			C _L = 15 pF	5 V		45						IVITIZ
	CLKBA or	A or B	$C_{L} = 50 \text{ pF}$	4.5 V			44		66		55	
	CLKAB	AUID	C _L = 15 pF	5 V		18						
. .	A or B	B or A	$C_L = 50 pF$	4.5 V			37		56		46	ns
^t pd	AUID	BULY	C _L = 15 pF	5 V		15						115
	SBA or	A or B	$C_L = 50 pF$	4.5 V			46		69		58	
	SAB†	AUID	C _L = 15 pF	5 V		19						
	ŌĒ	A or B	$C_L = 50 pF$	4.5 V			45		68		56	ns
^t en	OE	AUID	C _L = 15 pF	5 V		19						115
+	ŌĒ	A or B	C _L = 50 pF	4.5 V			35		53		44	ns
^t dis	OE .	AUID	C _L = 15 pF	5 V		14						115
t _t			$C_{L} = 50 \text{ pF}$	4.5 V			12		18		15	ns

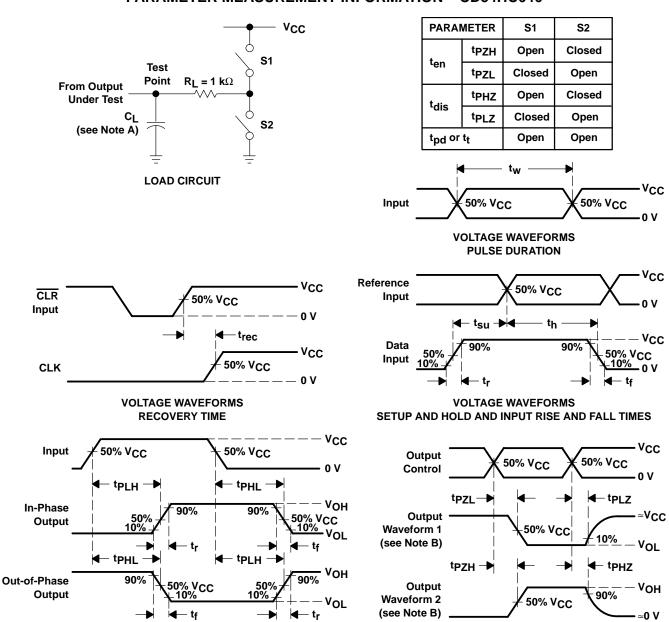
[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER				
Ср	Power dissipation capacitance	52	pF		



PARAMETER MEASUREMENT INFORMATION - CD54HC646



NOTES: A. C_L includes probe and test-fixture capacitance.

VOLTAGE WAVEFORMS

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.

VOLTAGE WAVEFORMS

OUTPUT ENABLE AND DISABLE TIMES

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

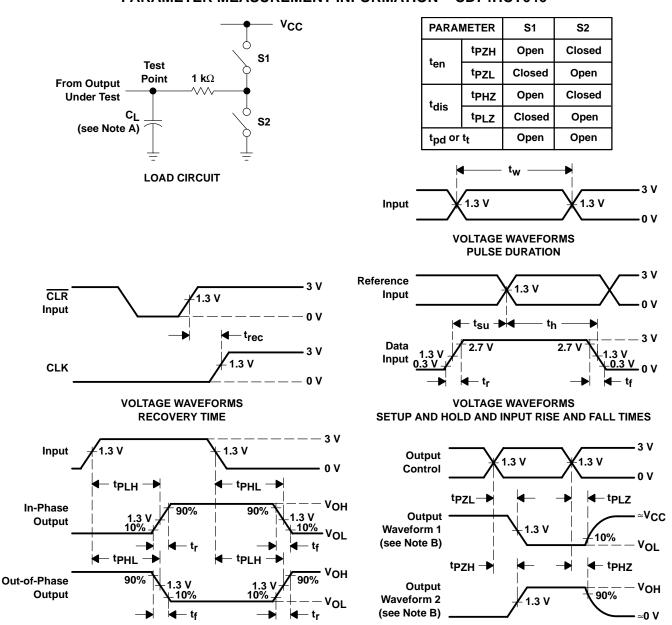
Figure 2. Load Circuit and Voltage Waveforms



VOLTAGE WAVEFORMS

OUTPUT ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION - CD74HCT646



NOTES: A. C_L includes probe and test-fixture capacitance.

VOLTAGE WAVEFORMS

PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLZ and tpHZ are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



5-Sep-2011

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-8688501JA	ACTIVE	CDIP	J	24	1	TBD	Call TI	Call TI	
CD54HC646F3A	ACTIVE	CDIP	J	24	1	TBD	Call TI	N / A for Pkg Type	
CD74HCT646M96	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT646M96E4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT646M96G4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54HC646:



PACKAGE OPTION ADDENDUM

5-Sep-2011

• Catalog: CD74HC646

NOTE: Qualified Version Definitions:

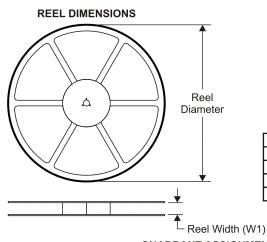
• Catalog - TI's standard catalog product

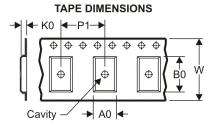




om 11-Mar-2008

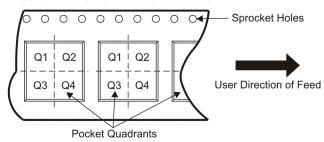
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

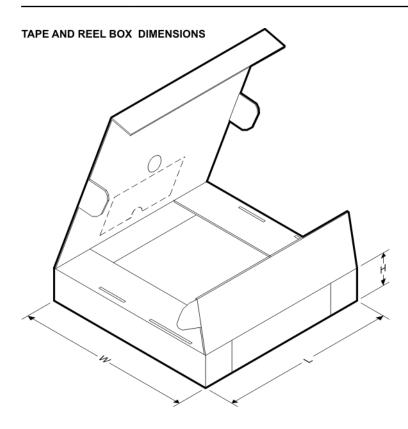


*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HCT646M96	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

11-Mar-2008



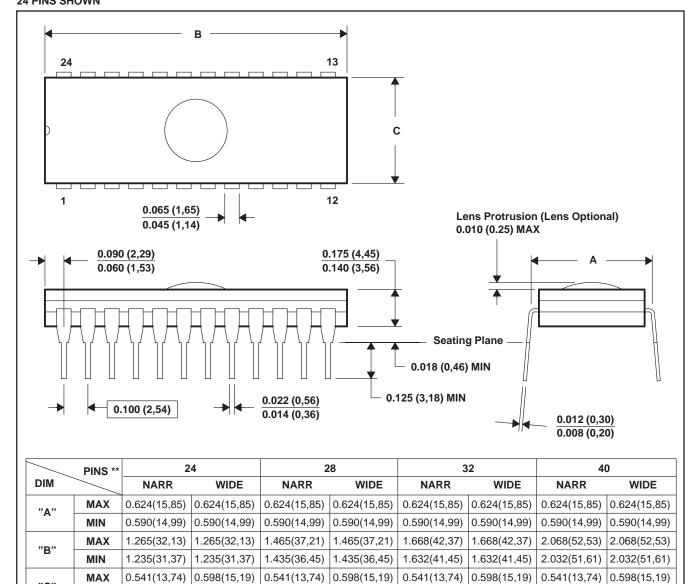
*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	CD74HCT646M96	SOIC	DW	24	2000	346.0	346.0	41.0	

J (R-GDIP-T**)

24 PINS SHOWN

CERAMIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

0.514(13,06)

"C"

MIN

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).

0.571(14,50)

D. This package can be hermetically sealed with a ceramic lid using glass frit.

0.514(13,06)

0.571(14,50)

0.514(13,06)

0.571(14,50)

0.514(13,06) | 0.571(14,50)

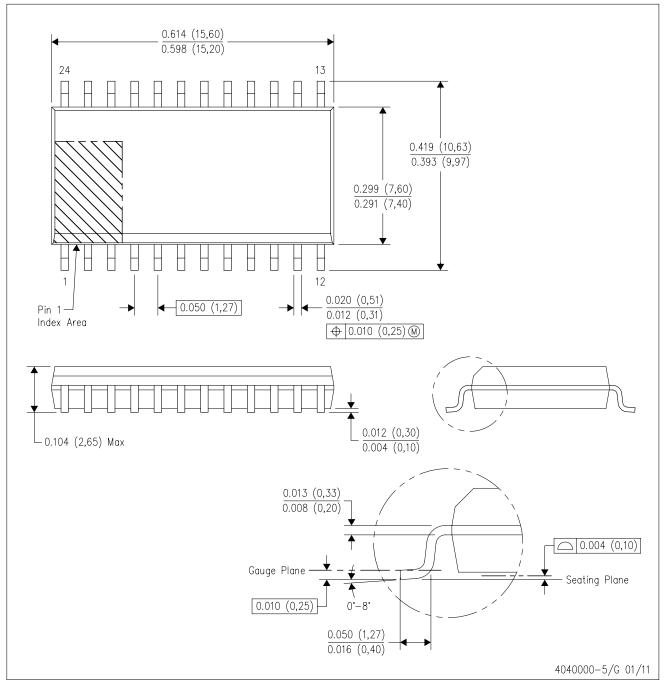
4040084/C 10/97

E. Index point is provided on cap for terminal identification.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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